

Automotive MOSFET

OptiMOS™ 6 Power-Transistor



Features

- OptiMOS™ power MOSFET for automotive applications
- N-channel - Enhancement mode - Normal Level
- Extended qualification beyond AEC-Q101
- PPAP Capable
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- RoHS compliant
- 100% Avalanche tested

Potential Applications

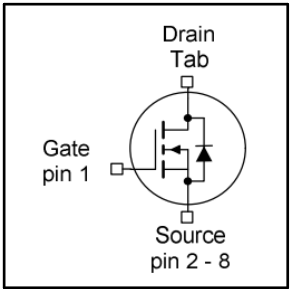
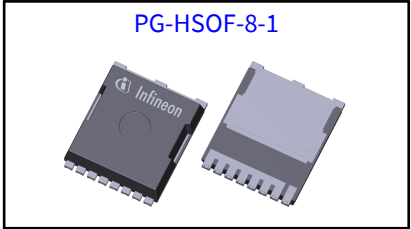
General automotive applications.

Product Validation

Qualified for automotive applications. Product validation according to AEC-Q101.

Product Summary

V_{DS}	150	V
$R_{DS(on)}$	3.8	mΩ
I_D (chip limited)	170	A



Type	Package	Marking
IAUTN15S6N038	PG-HSOF-8-1	6N15N038

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Maximum Ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$V_{GS} = 10\text{ V}$, Chip limitation ^{1,2)}	170	A
		$V_{GS} = 10\text{ V}$, DC current	170	
		$T_a = 100^\circ\text{C}$, $V_{GS} = 10\text{ V}$, R_{thJA} on 2s2p ^{2,3)}	24	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C = 25^\circ\text{C}$, $t_p = 100\text{ }\mu\text{s}$	601	
Avalanche energy, single pulse ²⁾	E_{AS}	$I_D = 85\text{ A}$	285	mJ
Avalanche current, single pulse	I_{AS}	–	170	A
Gate source voltage	V_{GS}	–	± 20	V
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$	263	W
Operating temperature	T_j	–	-55 ... +175	$^\circ\text{C}$

Thermal Characteristics²⁾

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	–	–		0.57	K/W
Thermal resistance, junction - ambient ³⁾	R_{thJA}	–	–	15.0	–	

Electrical Characteristics

 at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Static Characteristics

Drain-source breakdown voltage	$V_{(Br)DSS}$	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	150	–	–	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 166\text{ }\mu\text{A}$	3	3.5	4	
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 120\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 25^\circ\text{C}$	–	–	1	μA
		$V_{DS} = 120\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 100^\circ\text{C}^{2)}$	–	–	100	
Gate-source leakage current	I_{GSS}	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$	–	–	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 8\text{ V}$, $I_D = 43\text{ A}$	–	3.7	4.8	m Ω
		$V_{GS} = 10\text{ V}$, $I_D = 85\text{ A}$	–	3.3	3.8	
Gate resistance ²⁾	R_G	–	–	1.0	–	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics ²⁾						
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 75\text{ V}, f = 1\text{ MHz}$	–	4760	6200	pF
Output capacitance	C_{oss}		–	1370	1780	
Reverse transfer capacitance	C_{rss}		–	27	40	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 75\text{ V}, V_{GS} = 10\text{ V},$ $I_D = 85\text{ A}, R_G = 3.5\text{ }\Omega$	–	17	–	ns
Rise time	t_r		–	36	–	
Turn-off delay time	$t_{d(off)}$		–	26	–	
Fall time	t_f		–	33	–	

Gate Charge Characteristics²⁾						
Gate to source charge	Q_{gs}	$V_{DD} = 75\text{ V}, I_D = 85\text{ A},$ $V_{GS} = 0\text{ to }10\text{ V}$	–	26	33	nC
Gate to drain charge	Q_{gd}		–	17	25	
Gate charge total	Q_g		–	67	88	
Gate plateau voltage	$V_{plateau}$		–	5.4	–	V

Reverse Diode						
Diode continuous forward current ²⁾	I_S	$T_C = 25^\circ\text{C}$	–	–	170	A
Diode pulse current ²⁾	$I_{S,pulse}$	$T_C = 25^\circ\text{C}, t_p = 100\ \mu\text{s}$	–	–	601	
Diode forward voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_F = 85\text{ A}, T_j = 25^\circ\text{C}$	–	0.9	1.0	V
Reverse recovery time ²⁾	t_{rr}	$V_R = 75\text{ V}, I_F = 50\text{ A}$ $di_F/dt = 100\text{ A}/\mu\text{s}$	–	33	50	ns
Reverse recovery charge ²⁾	Q_{rr}		–	16	32	nC

¹⁾ Practically the current is limited by the overall system design including the customer-specific PCB.

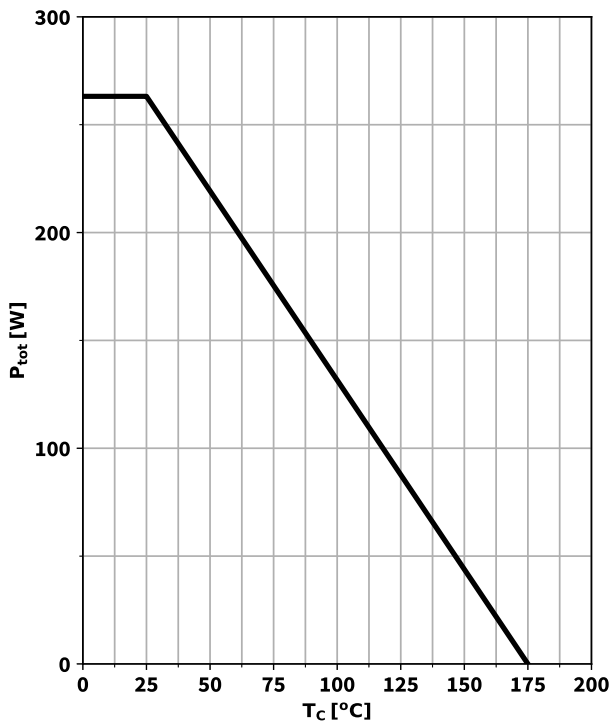
²⁾ The parameter is not subject to production testing – specified by design.

³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

Electrical characteristics diagrams

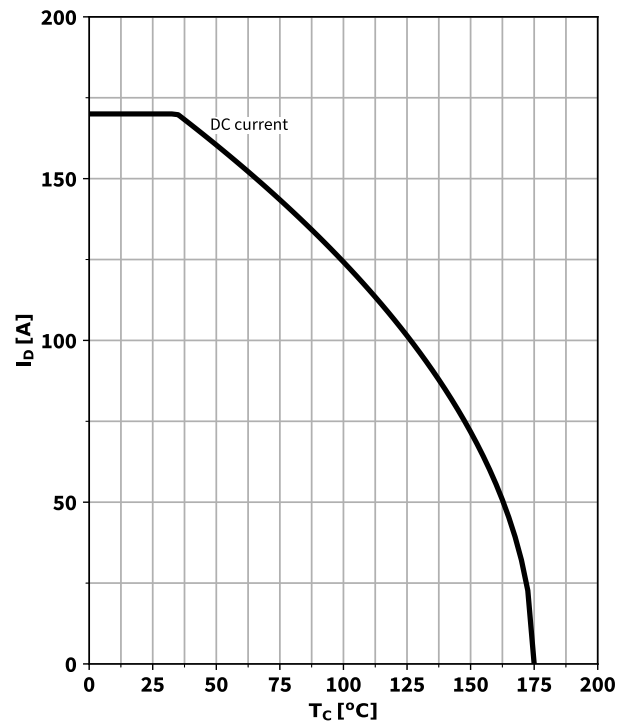
1 Power dissipation

$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



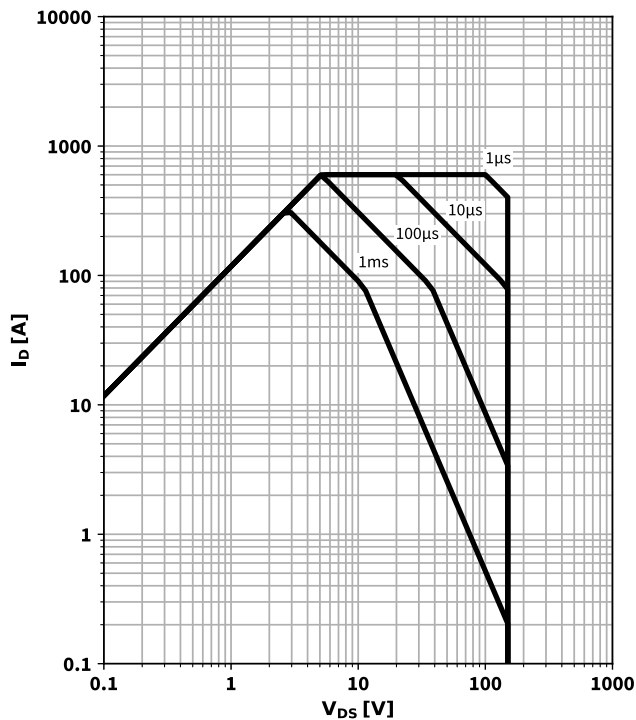
2 Drain current

$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



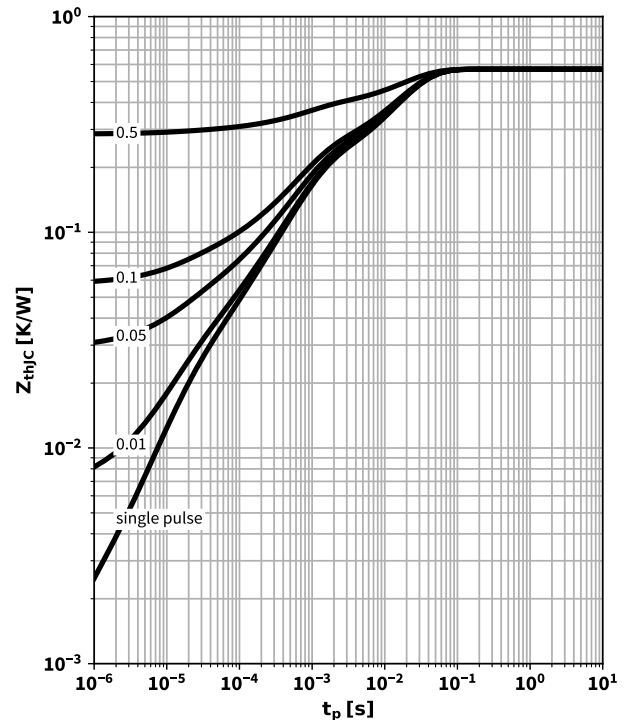
3 Safe operating area

$$I_D = f(V_{\text{DS}}); T_C = 25^{\circ}\text{C}; D = 0; \text{parameter: } t_p$$



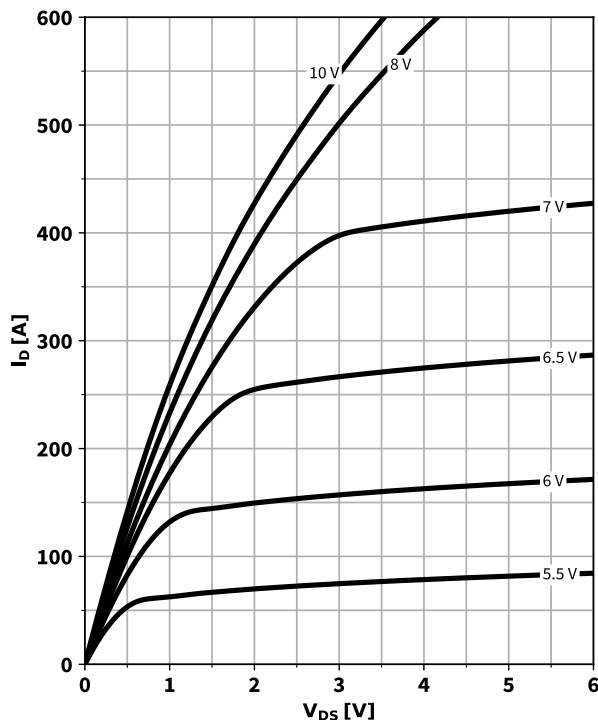
4 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p); \text{parameter: } D = t_p/T$$



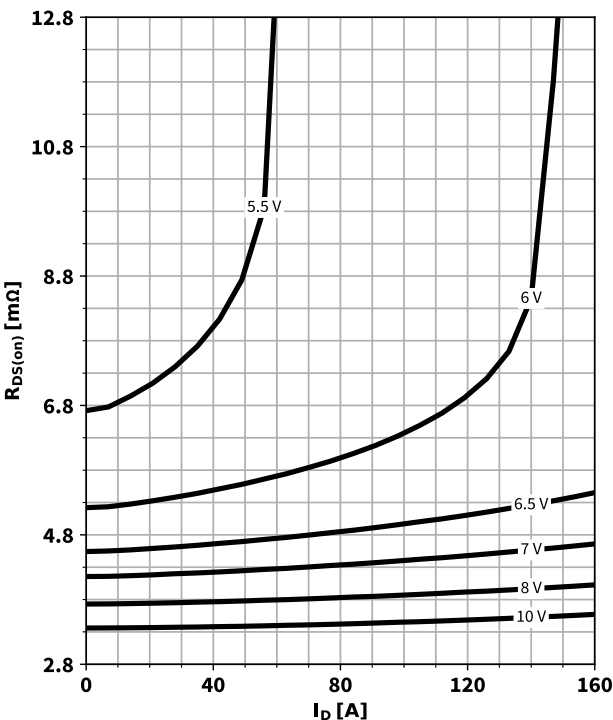
5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25^\circ\text{C}$; parameter: V_{GS}



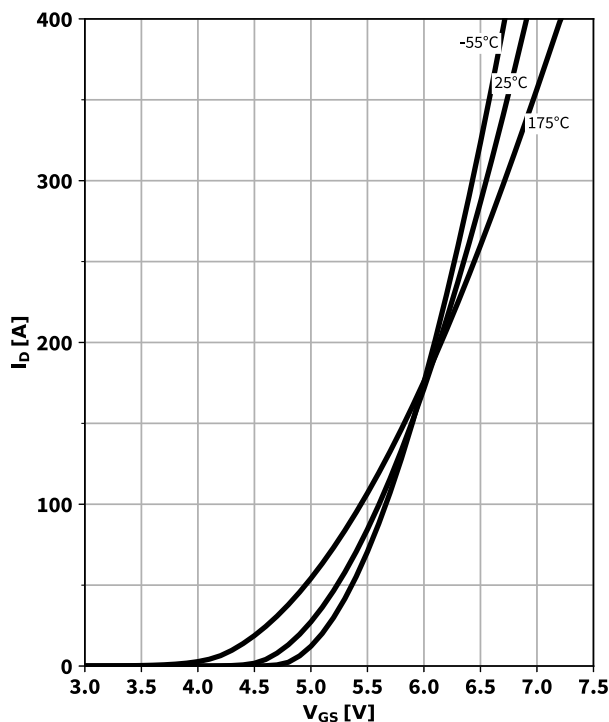
6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D)$; $T_j = 25^\circ\text{C}$; parameter: V_{GS}



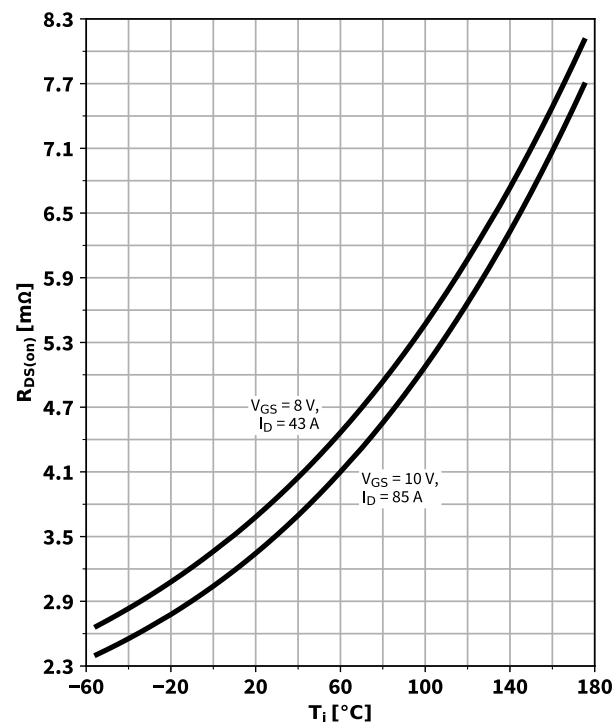
7 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} = 6\text{ V}$; parameter: T_j



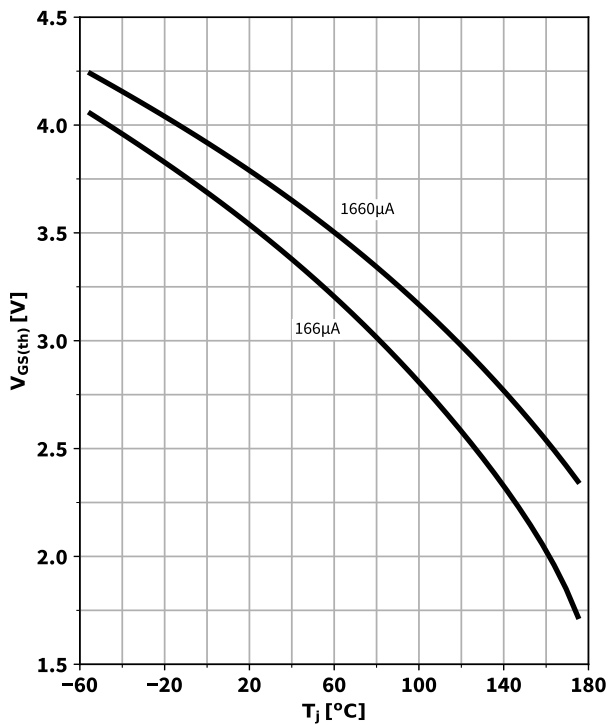
8 Typ. drain-source on-state resistance

$R_{DS(on)} = f(T_j)$; parameter: I_D , V_{GS}



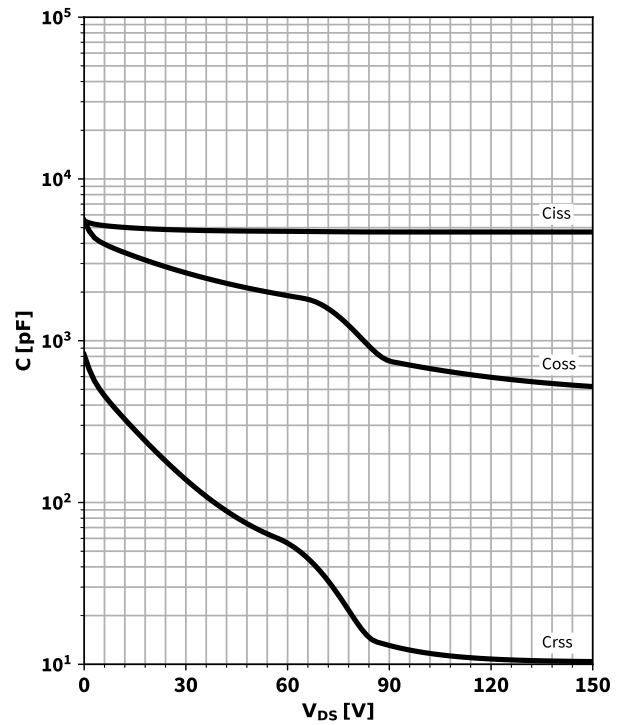
9 Typ. gate threshold voltage

$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$; parameter: I_D



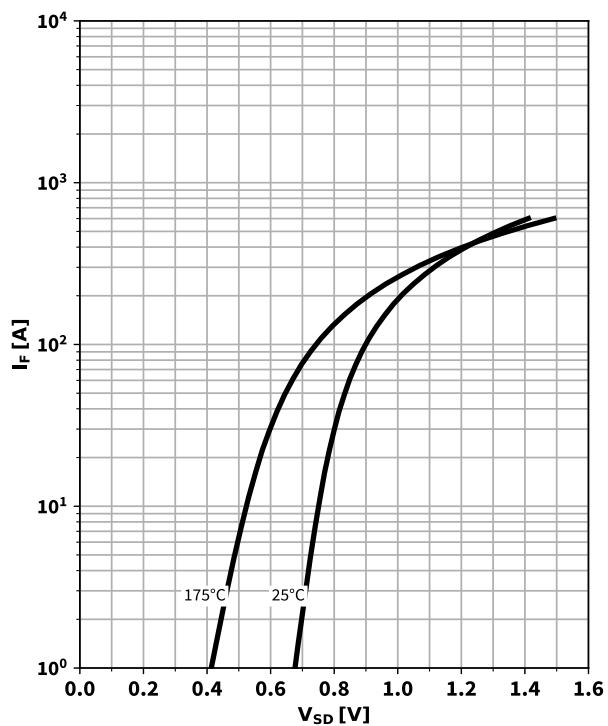
10 Typ. capacitances

$C = f(V_{DS})$; $V_{GS} = 0 V$; $f = 1 MHz$



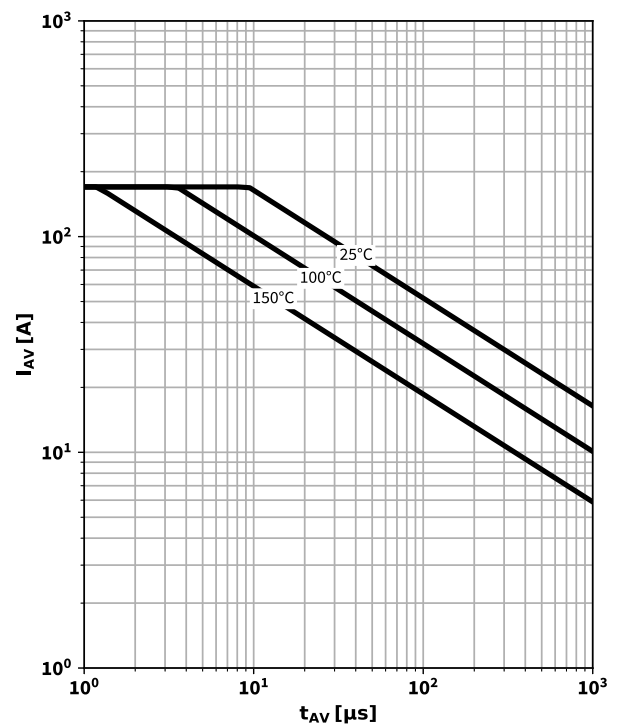
11 Typ. forward diode characteristics

$I_F = f(V_{SD})$; parameter: T_j



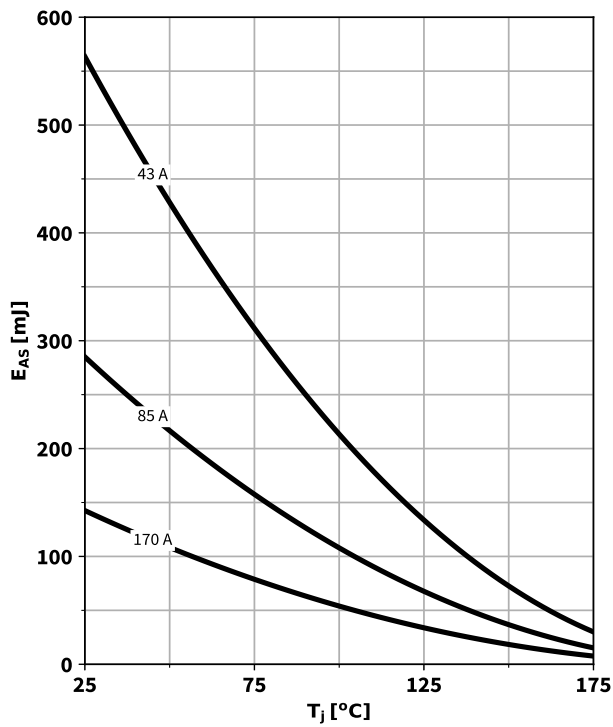
12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$; parameter: $T_{j(start)}$



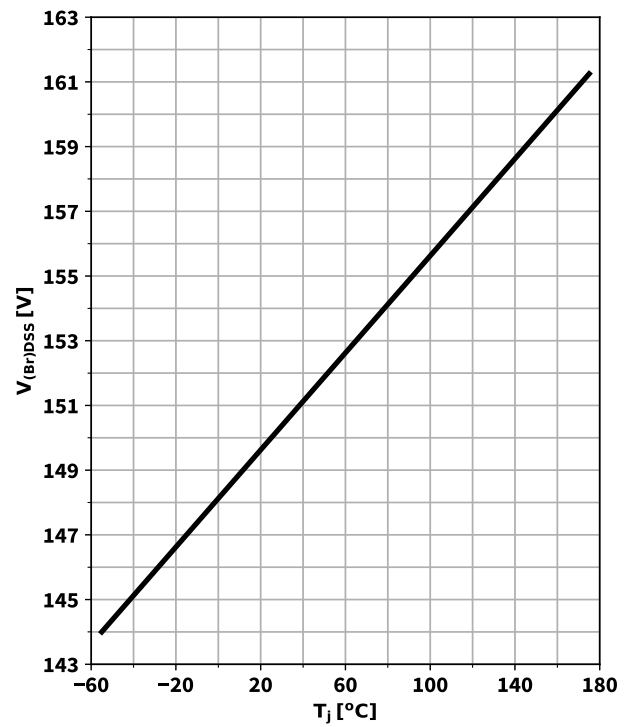
13 Typical avalanche energy

$E_{AS} = f(T_j)$; parameter: I_D



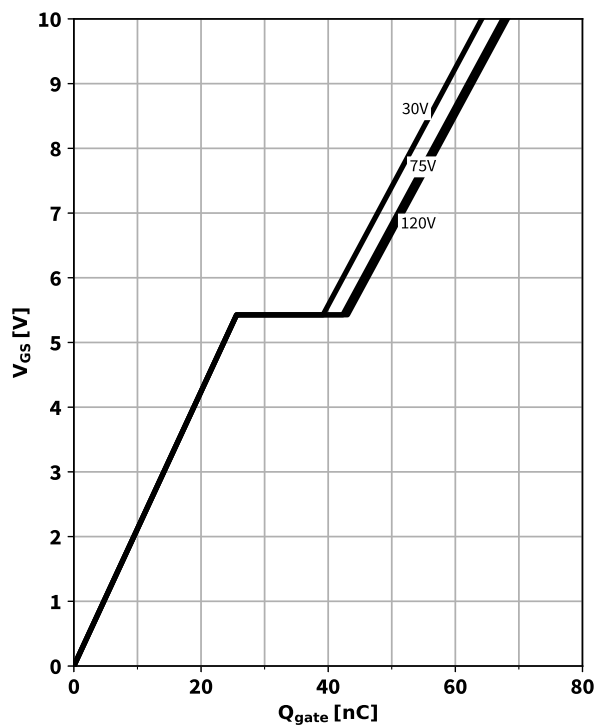
14 Drain-source breakdown voltage

$V_{(Br)DSS} = f(T_j)$; $I_D = 10$ mA



15 Typ. gate charge

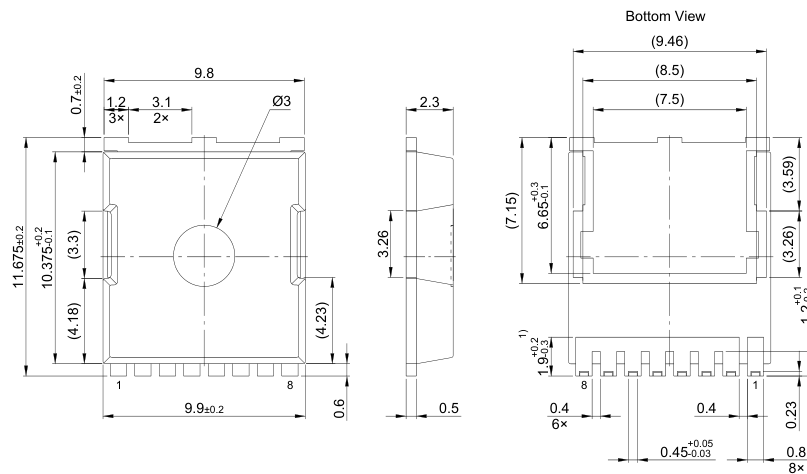
$V_{GS} = f(Q_{gate})$; $I_D = 85$ A pulsed; parameter: V_{DD}



16 Gate charge waveforms



Package Outline



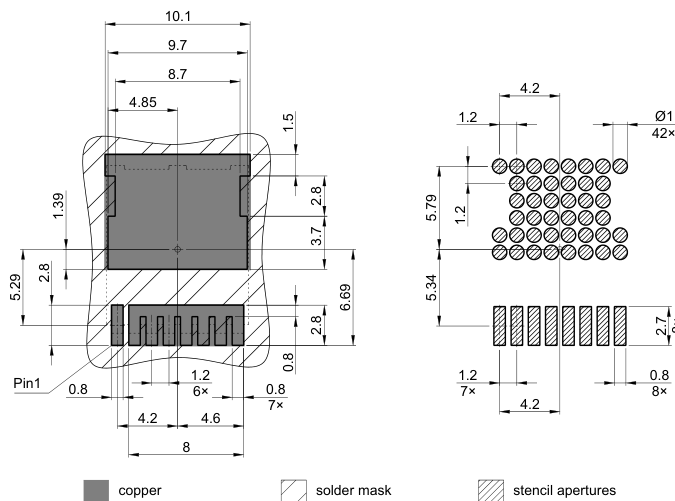
1) Lead length up to anti flash profile; mold flashes excluded.

All dimensions are in units mm

The drawing is in compliance with ISO 128-30, Projection Method 1 [⊥]

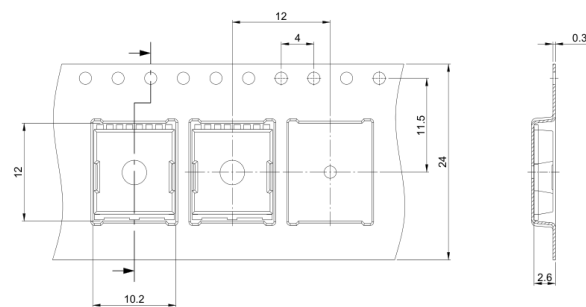
Drawing according to ISO 8015, general tolerances ±0.1; ±1°30'

Footprint



All dimensions are in units mm
All pads are solder mask defined

Packaging



All dimensions are in units mm
The drawing is in compliance with ISO 128-30, Projection Method 1 [⊥]

Revision History

Revision	Date	Changes
Revision 1.0	30.04.2025	Final data sheet

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Email: erratum@infineon.com

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